

## **Amendments to the Specification**

Please amend paragraph [0087] beginning on page 34 as follows:

[0087] In one implementation, the invention comprises a substrate susceptor for receiving a semiconductor substrate to be deposited upon, for example and by way of example only, as indicated with reference numeral 120 in Figs. 17-20. Substrate susceptor 120 has a body 121 comprising a front substrate receiving side 122, a back side 124 and a peripheral edge 126. At least three movable substrate edge clamps are associated with the body, and are positioned to engage a peripheral edge of a semiconductor substrate received by the body for deposition thereupon. For example, Figs. 17 and 18 depict a substrate 31 to be deposited upon comprising a peripheral edge 127. (Fig. 18). Four movable substrate edge clamps 130 are received over front side 122, and shown in a non-engaging position relative to substrate 31 in Figs. 17 and 18. Edge clamps 130 comprise a pivot shaft 132 extending through body 121 with, in the depicted exemplary embodiment, shaft 132 being formed

about or defining a pivot axis 123 to which individual clamping devices or portions are mounted/received for clamping engagement relative to substrate 31. Susceptor body 121 comprises a rotation axis 136 about which susceptor 120 rotates, and which is preferably parallel with the pivot axis 123 of shaft 132.